

Claims

1. A method for completely or partly covering at least one electronic component with a compound, wherein in a suitable order, the following steps are traversed:
 - a) the at least one electronic compound is placed on a mold half;
 - 5 b) the electronic compound is completely or partly covered with the compound;
 - c) a second mold half which is moveable relative to the first mold half is moved in the direction of the first mold half;**characterized in that**
 - 10 e) the distance between the two mold halves is continuously regulated and, if desired, adjusted during the two mold halves being moved towards each other and during the two mold halves being held in a position when moved towards each other during the curing of the compound.
2. A method according to claim 1, wherein, in the position when moved
15 towards each other, the mold halves are held at a small distance from each other, so that in the position when moved towards each other too, a certain position control range is maintained.
3. A method according to claim 1 or 2, wherein step b) takes place after the mold halves have been brought into the position when moved towards each
20 other.
4. A method according to claim 3, wherein the compound is injected into the mold cavity.
5. A method according to claim 3, wherein the compound is placed in the mold cavity and during the mold halves being moved towards each other is
25 compressed so as to be spread in the mold cavity.

6. A method according to claim 1 or 2, wherein step b) takes place before the mold halves have been brought into the position when moved towards each other.

7. A method according to claim 6, wherein the compound is placed on the electronic component and, together with the component, is placed on the mold half.

8. A method according to claim 7, wherein the placement of the compound is effected by an inkjet technique, so that the compound is placed on the desired positions on the electronic component.

9. A method according to any one of the preceding claims, wherein a film is placed between the electronic component and at least one mold half.

10. A method according to claim 9, wherein the film also serves for supplying and/or discharging the electronic component into or from the mold cavity, respectively.

11. An apparatus for carrying out the method according to any one of the preceding claims, wherein the apparatus is provided with a first mold half and a second mold half, wherein the first mold half is moveable relative to the second mold half, while means are provided for placing an electronic component on a mold half for inclusion of the component in a mold cavity defined by the two mold halves, characterized in that the first mold half is provided with a number of actuators with the aid of which the position of the first mold half relative to the second mold half is continuously and accurately regulable, the apparatus being provided with a control for regulating the positions of said number of actuators, so that the distance between the two mold halves is continuously regulated, and, if desired, adjusted during the two mold halves being moved towards each other and during the two mold halves being held in a position when moved towards each other.

12. An apparatus according to claim 11, wherein the control is arranged for holding the two mold halves at a small distance from each other in the

position when moved towards each other, so that in the position when moved towards each other too, a certain position control range is maintained.

13. An apparatus according to claim 11 or 12, wherein a component supply and discharge device is provided, which is arranged for placing and removing
5 an electronic component on or from said mold half, respectively.

14. An apparatus according to any one of claims 11 – 13, wherein a film supply and discharge device is provided for supplying film to the mold cavity and discharging film from the mold cavity.

15. An apparatus according to claims 13 and 14, wherein the film supply
10 and discharge device also forms the component supply device.

16. An apparatus according to any one of claims 11 – 15, provided with a compound supply provision.

17. An apparatus according to claim 16, wherein the compound supply provision is arranged for supplying the compound to the mold cavity when the
15 mold halves are in the position when moved towards each other.

18. An apparatus according to claim 16, wherein the compound supply provision is arranged for placing the compound on an electronic component which is placed on a mold half.

19. An apparatus according to claim 16, wherein the compound supply
20 provision is arranged for placing compound on an electronic component present outside the mold cavity.

20. An apparatus according to claim 18 or 19, wherein the compound supply provision comprises an inkjet head and a compound reservoir connected to the inkjet head.